

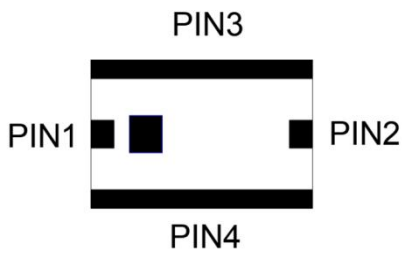
### Features

- Multilayer monolithic construction yields high reliability
- Low insertion loss and small size SMD chip design
- Can simplify your complex tuning and circuit design
- LTCC process

### Specifications

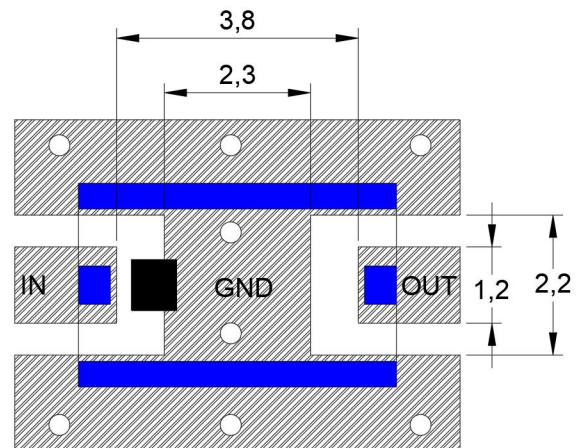
NO.	Parameter	Frequency (MHz)	SPEC	
			Min.	Max.
1	Insertion Loss (dB)	800~1300		3.0
2	Ripple (dB)	800~1300		2.0
2	Attenuation (dBc)	DC~600	35	
		1500~6000	40	
3	VSWR	800~1300		2.0
6	In/Output Impedance ( $\Omega$ )	50		

### Construction



PIN	Connection
1	Input Port
2	Output Port
3	GND
4	GND

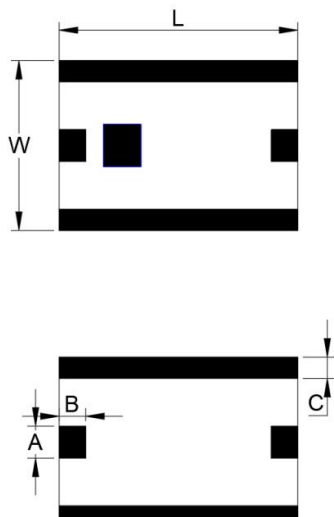
### Mounting Considerations



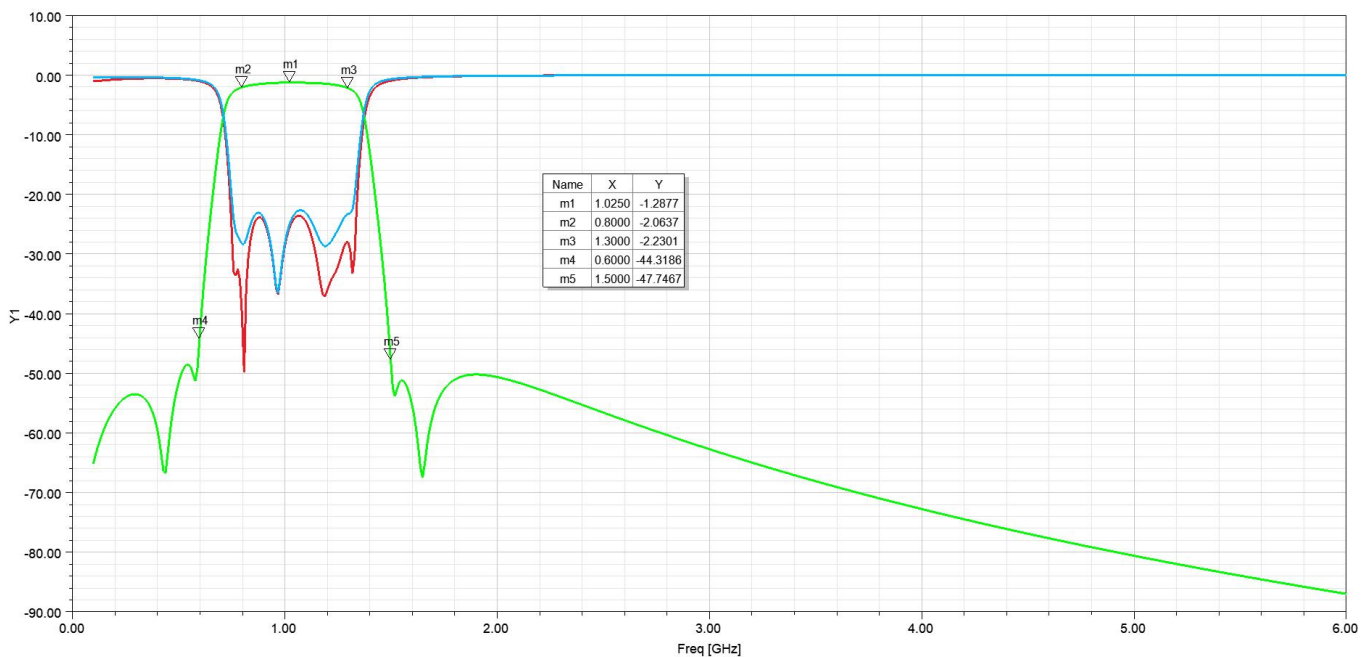
Unit: mm

Line width to be designed to match 50  $\Omega$  characteristic impedance, depending on PCB material and thickness

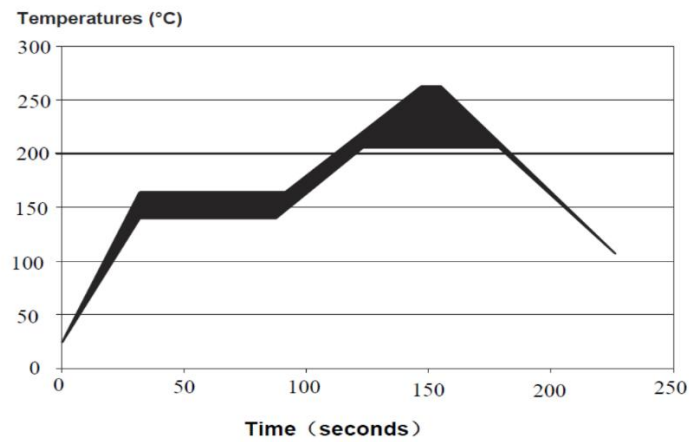
### Dimensions

Figure	Symbol	Dimension (mm)
	L	5.00±0.20
	W	3.20±0.20
	T	1.50±0.20
	A	0.60±0.10
	B	0.40±0.10
	C	0.40±0.10

### Typical Electrical Characteristics (T=25°C)



### Solder Reflow Standard Conditioning



### Storage Conditions

Temperature : +5 to +30 °C

Humidity : 20 to 70% RH

Term of storage : Within 12 months (After the delivery) \*

Baking : Unnecessary

\* After peeling off cover tape, do not keep exposing the products to the open air. For the products stored longer than 12 months, confirm their terminals and solderability before use.